



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-09-05
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		


Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TDA75610S-ZSX	A9ZS*UK99AA6	A	MU1A	2013-09-05
	Amount	UoM	Unit type	ST ECOPACK Grade
	1925.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	11x15.7x3.14	36	flat	
Comment				

Material Composition Declaration						Mfr Item Name	A9ZS*UK99AA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	26.390	mg	supplier	die	Silicon (Si)	7440-21-3		26.202	mg	992876	13611
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.015	mg	568	8
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.040	mg	1516	21
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.133	mg	5040	69
Leadframe	Copper & its alloys	1268.077	mg	supplier	alloy	Copper (Cu)	7440-50-8		1263.151	mg	996115	656182
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.582	mg	459	302
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		1.062	mg	837	552
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		3.282	mg	2588	1705
Bonding wire				supplier	wire	Copper (Cu)	7440-50-8		3.604	mg	1000000	1872
encapsulation		621.472	mg	supplier	mold compound	Phenol Resin	205830-20-2		24.859	mg	40000	12914
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		18.645	mg	30001	9686
encapsulation				supplier	mold compound	epoxy resin	na		18.645	mg	30001	9686
encapsulation				supplier	mold compound	carbon black	1333-86-4		1.243	mg	2000	646
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		558.080	mg	897997	289912